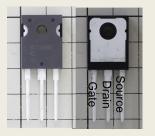


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# RHOM SCT3080HLHR AUTOMOTIVE CERTIFIED 1200V SiC MOSFET SHORT CIRCUIT ROBUSTNESS ANALYSIS REPORT

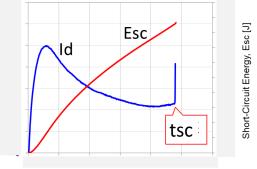
*February 2020.* The short-circuit (SC) capability of power transistors, especially SiC power MOSFETs, is one of the most critical reliability-related specifications. Compared to Si-based IGBTs, the size of the SiC transistor is smaller. This leads to significant reduction in SC endurance time (tsc). Current Id [A] @ Vds=600V





New

Release



Time, t [us]

Package

**Die image** 

Drain current waveform and short-circuit energy (Esc)

This is the first published short-circuit robustness analysis report that examines the correlation between short circuit robustness and the physical structure of the SCT3080HLHR device. This device is compliant to the AEC Q101 automotive standard.

Drain

### The report includes:

- Identification of the mechanisms limiting short-circuit capability, measurement, physical analysis results, and extraction of the critical temperature (Tj(crit)) at the onset of failure.
- Comparison of short-circuit robustness with other makers' 1200V SiC MOSFETs. Examination of the differences in semiconductor structure, process, and their effect on short circuit robustness.
- Comparison of the electrical characteristics (off-leakage current and temperature) dependence) and identification of differences and limitations.

#### Use value of the evaluation results in this report

- The minimum response time of the short-circuit protection circuit can be estimated.
- The internal device temperature can be estimated by performing electrothermal SPICE simulation using measured short-circuit drain current waveform and endurance time  $(t_{sc}, t)$ .

# Report price: \$6,500

Contact LTEC Corporation for the current price as it decreases over time

19G-0019-1



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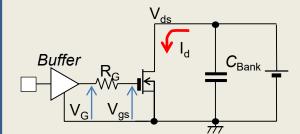
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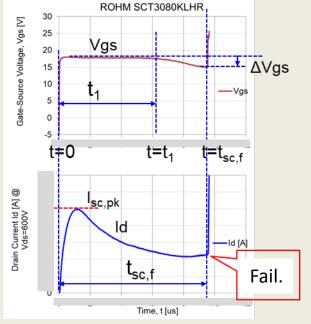


## **Excerpts from the report**





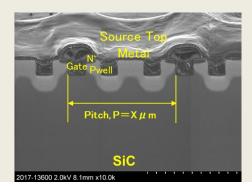


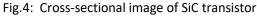


**Fig.17**: Measured gate-source voltage and drain current waveforms during SC event.

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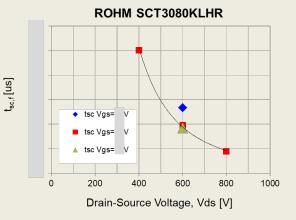
Short-Circuit Time-to-Failure,





#### Table 2: Evaluation conditions

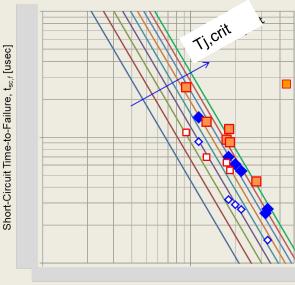
#	Vds [V]	Vgs [V]	Purpose
1	600	18	Basic SC characteristics
2	600	18	Reproducibility check
3	400	18	Drain voltage effect
4	800	18	"
5	600	15	Gate-Source voltage effect
6	600	20	"
7	600	24	"



**Fig.18**: Measured dependence of the SC time to failure  $t_{sc,f}$  vs the drain voltage Vds.

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### **Excerpts from the report (cont.)**



Dissipated Power Density, P<sub>d</sub>/A [W/mm<sup>2</sup>]

Fig.28:Measured short circuit durable time (t<sub>sc.f</sub>) vs. Power dissipation density Pd/A=(Vds x Id)/A.

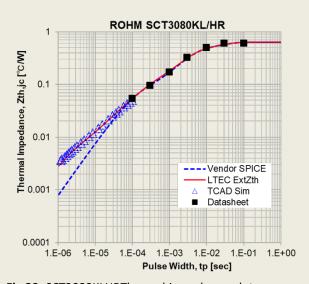


Fig.29: SCT3080KLHRThermal impedance plot : Data from the datasheet, Blue dash line): Calculated using the SPICE model

provided by manufacturer, and  $\triangle$  Calculated using the analysis result by LTEC Red line: LTEC synthesized SPICE model

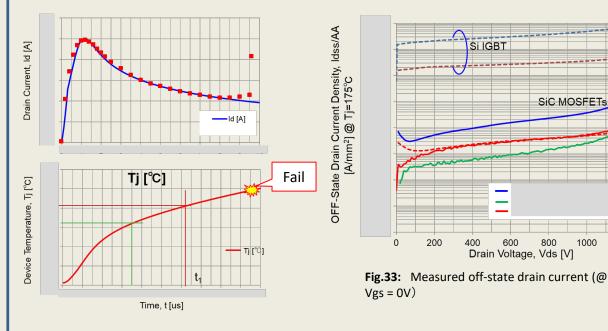


Fig.30: Extracted transistor temperature rise using short circuit transient SPICE model

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1000

1200